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Stocking Distributor

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[Diodes Incorporated](#)
[MMBD4448DW-7](#)

For any questions, you can email us directly:

sales@integrated-circuit.com



MMBD4448DW

SURFACE MOUNT SWITCHING DIODE

Features

- Fast Switching Speed
- Surface Mount Package Ideally Suited for Automated Insertion
- For General Purpose Switching Applications
- High Conductance
- Miniature Package
- **Lead Free/RoHS Compliant (Note 1)**
- **Qualified to AEC-Q101 Standards for High Reliability**
- **"Green" Device (Notes 2 and 3)**

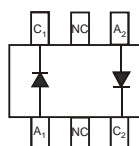
Mechanical Data

- Case: SOT-363
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish annealed over Alloy 42 leadframe (Lead Free Plating). Solderable per MIL-STD-202, Method 208
- Polarity: See Diagram
- Weight: 0.006 grams (approximate)

SOT-363



Top View



Top View
Internal Schematic

Ordering Information (Note 4)

Part Number	Case	Packaging
MMBD4448DW-7-F	SOT-363	3000/Tape & Reel

- Notes:
1. No purposefully added lead.
 2. Diodes Inc.'s "Green" policy can be found on our website at <http://www.diodes.com>.
 3. Product manufactured with Date Code UO (week 40, 2007) and newer are built with Green Molding Compound. Product manufactured prior to Date Code UO are built with Non-Green Molding Compound and may contain Halogens or Sb2O3 Fire Retardants.
 4. For packaging details, go to our website at <http://www.diodes.com>.

Marking Information



KA3 = Product Type Marking Code
 YM = Date Code Marking
 Y = Year (ex: N = 2002)
 M = Month (ex: 9 = September)

Date Code Key

Year	2000	2001	2002	2003	2004	2005	2006	2007	2008	2009	2010	2011	2012	2013	2014	2015
Code	L	M	N	P	R	S	T	U	V	W	X	Y	Z	A	B	C
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec				
Code	1	2	3	4	5	6	7	8	9	O	N	D				



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Maximum Ratings @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Non-Repetitive Peak Reverse Voltage	V _{RM}	100	V
Peak Repetitive Reverse Voltage	V _{R(RM)}	75	V
Working Peak Reverse Voltage	V _{R(WM)}		
DC Blocking Voltage	V _R		
RMS Reverse Voltage	V _{R(RMS)}	53	V
Forward Continuous Current (Note 5)	I _{FM}	500	mA
Average Rectified Output Current (Note 5)	I _O	250	mA
Non-Repetitive Peak Forward Surge Current	I _{FSM}	@ t < 1μs	4
		@ t < 1s	1

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	P _D	200	mW
Thermal Resistance Junction to Ambient Air (Note 5)	R _{θJA}	625	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-65 to +150	°C

Electrical Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 6)	V _{(BR)R}	75	—	V	I _R = 10μA
Forward Voltage	V _F	0.62	0.720	V	I _F = 5.0mA
		—	0.855		I _F = 10mA
		—	1.0		I _F = 50mA
		—	1.25		I _F = 150mA
Reverse Current (Note 6)	I _R	—	2.5	μA	V _R = 75V
		—	50	μA	V _R = 75V, T _J = 150°C
		—	30	μA	V _R = 25V, T _J = 150°C
		—	25	nA	V _R = 20V
Total Capacitance	C _T	—	4.0	pF	V _R = 0, f = 1.0MHz
Reverse Recovery Time	t _{rr}	—	4.0	ns	I _F = I _R = 10mA, I _{rr} = 0.1 x I _R , R _L = 100Ω

- Notes: 5. Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch; pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at <http://www.diodes.com>.
 6. Short duration pulse test used to minimize self-heating.

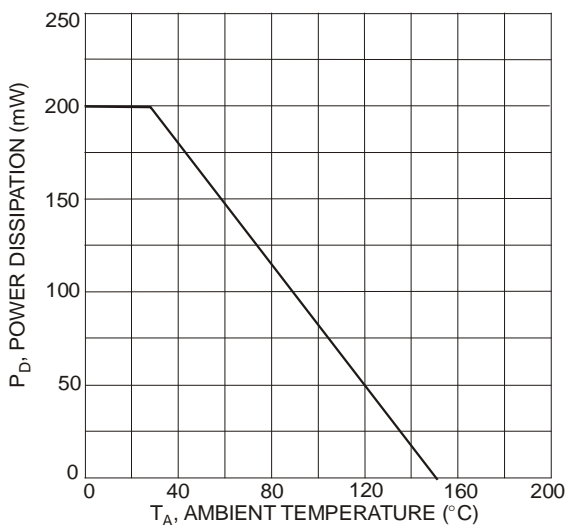


Fig. 1 Power Derating Curve, Total Package (Note 5)

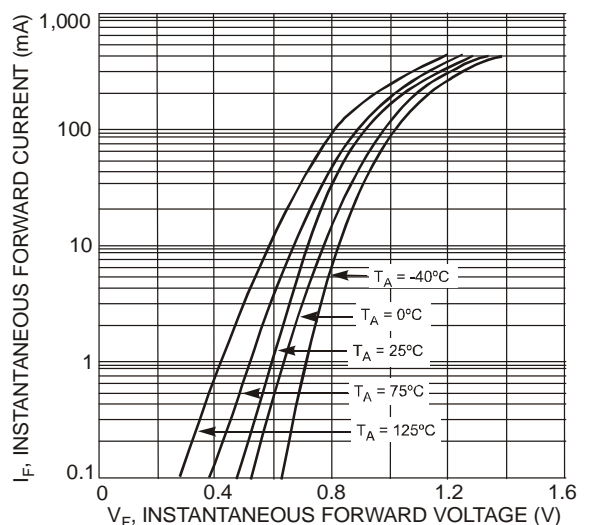


Fig. 2 Typical Forward Characteristics, Per Element



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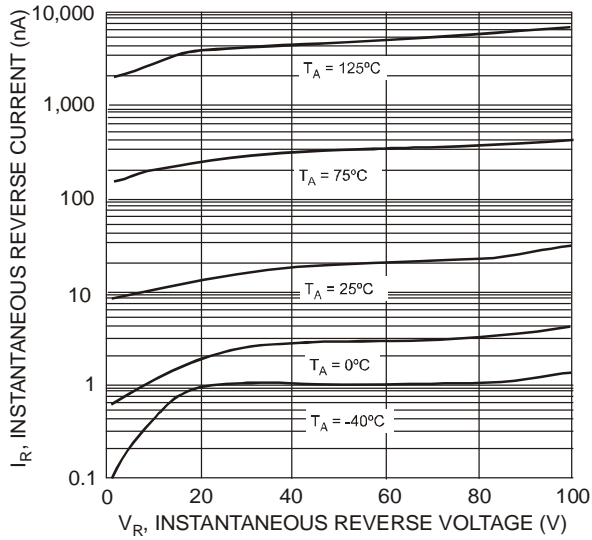


Fig. 3 Typical Reverse Characteristics, Per Element

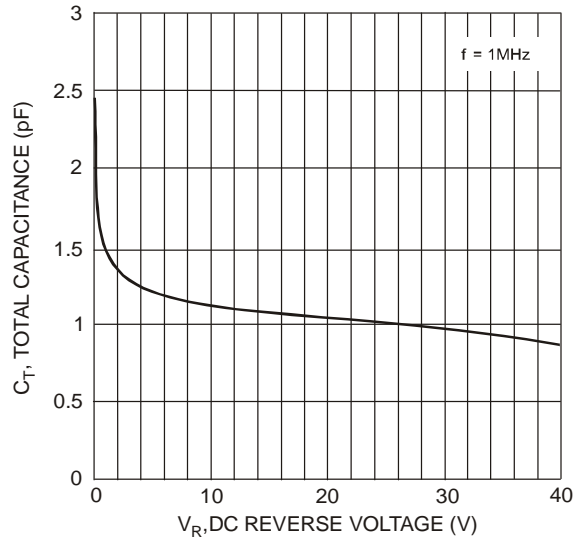
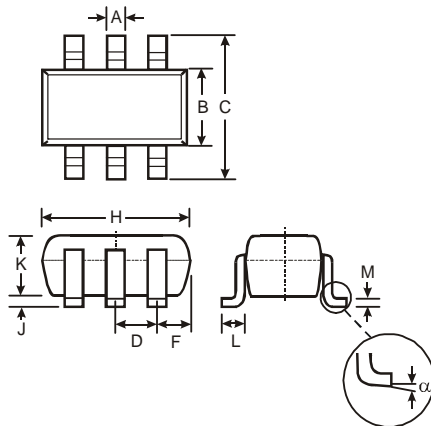


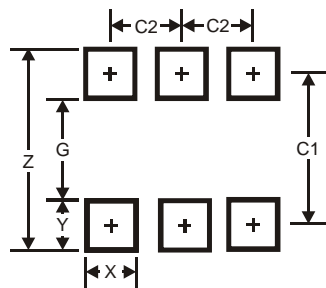
Fig. 4 Total Capacitance vs. Reverse Voltage, Per Element

Package Outline Dimensions



SOT-363		
Dim	Min	Max
A	0.10	0.30
B	1.15	1.35
C	2.00	2.20
D	0.65 Typ	
F	0.40	0.45
H	1.80	2.20
J	0	0.10
K	0.90	1.00
L	0.25	0.40
M	0.10	0.22
α	0°	8°
All Dimensions in mm		

Suggested Pad Layout



Dimensions	Value (in mm)
Z	2.5
G	1.3
X	0.42
Y	0.6
C1	1.9
C2	0.65

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